A step forward into multiplatform chip integration is developed in this master's thesis. Specifically, by using photonic wire bonding (PWB) as the bridge between InP laser sources and silicon-organic hybrid (SOH) based on a silicon on insulator (SOI) platform was developed. The master thesis focuses on the pre-characterization of optical devices, such as the laser sources and the modulator; the fabrication process of the optically-integrated device, including the aforementioned optical elements with the PWB; the post-characterization of the optically-integrated device, including optical path losses and data transmission performance; and finally, expecting to have a fully-integrated (i.e. optical and electrical), packaged device aiming for a commercially viable active optical cable (AOC) featuring 100G transfer data rate at a reasonable bit error ratio (BER